

What is claimed is:

1. A memory module comprising:

5 a board;

a memory device attached to the board; and

10 a heat dissipation means arranged between the memory device and the board.

2. The memory module of claim 1, wherein the heat dissipation means includes a heat-conducting paste between the board 10 and the memory device (12).

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3. The memory module of claim 1, wherein the heat dissipation means includes an area of the board at which solder varnish covering the board is removed.

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4. Memory module of claim 1, wherein the heat dissipation means includes a metal layer.

25 5. The memory module of claim 4, wherein the metal layer is connected to a supply line to which, in operation, a supply potential is applied.

6. The memory module of claim 4, wherein the metal layer includes a conductive trace.

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7. The memory module of claim 6, wherein the conductive trace is meander-shaped.

8. The memory module of claim 4, wherein the metal layer includes a heat sink.

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9. The memory module of claim 2, wherein the heat dissipation means includes a contact hole.

10. The memory module of claim 9, wherein the contact hole is connected to a supply line at which, in operation, a supply potential is applied.

5 11. The memory module of claim 1, further comprising a frame which is arranged at the edge of the board and comprises a heat-conductive material.

10 12. The memory module of claim 11, wherein the metal frame comprises taps by means of which same can be heat-conductively connected to a socket or a motherboard.